

SBIR 06.2 PHASE I - AWARD DETAILS	
ORGANIZATION	CERDEC
TOPIC NUMBER	A06-119
CONTRACT NUMBER	
YEAR OF AWARD	
AWARD START DATE	
AWARD COMPLETION DATE	
PROPOSAL NUMBER	A062-119-2512
TITLE	High Performance Thermal Transfer Material
PROJECT MANAGER	Alfiero (714) 530-2400 Nancy_Balzano@basicinc.com
COMPANY	Basic Electronics, Inc. 11371 Monarch Street Garden Grove CA 92841-1406 Minority Owned: No Veteran Owned: No Number of Employees: 45
KEYWORDS	Thermal Composite Material Thermal Management Electronic system weight reduction
ABSTRACT	Basic Electronics, Inc. has developed and patented a unique, composite material that provides significant potential for solving thermal problems and weight problems associated with current systems used to dissipate heat. This composite material conducts heat at rates of up to five times greater than that of copper and is approximately half the weight of aluminum. The purpose of this proposal is to demonstrate the performance of the thermal composite material in various configurations to resolve thermal management and weight problems in electronic systems.
BENEFITS	Properly configured, this composite material allows more efficient operation of increasingly miniaturized electronic systems and devices of all types. It also reduces weight in devices where excess weight is a performance constraint.